
**Polprevodniški elementi - Mikroelektromehanski elementi - 3. del: Standardni tankoplastni preskušaneč za preskušanje razteznosti (IEC 62047-3:2006)
(istoveten EN 62047-3:2006)**

Semiconductor devices - Micro electromechanical devices - Part 3: Thin film standard test piece for tensile-testing (IEC 62047-3:2006)

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**Semiconductor devices -
Micro-electromechanical devices
Part 3: Thin film standard test piece for tensile testing
(IEC 62047-3:2006)**

Dispositifs à semiconducteurs -
Dispositifs microélectromécaniques
Partie 3: Eprouvette d'essai normalisée
en couche mince pour l'essai de traction
(CEI 62047-3:2006)

Halbleiterbauelemente -
Bauteile der Mikrosystemtechnik
Teil 3: Dünnschicht-Standardmikroprobe
für die Prüfung der Zugbeanspruchung
(IEC 62047-3:2006)

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This European Standard was approved by CENELEC on 2006-09-01. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

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CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B - 1050 Brussels

Foreword

The text of document 47/1866/FDIS, future edition 1 of IEC 62047-3, prepared by IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 62047-3 on 2006-09-01.

The following dates were fixed:

- latest date by which the EN has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2007-06-01
- latest date by which the national standards conflicting with the EN have to be withdrawn (dow) 2009-09-01

Annex ZA has been added by CENELEC.

Endorsement notice

The text of the International Standard IEC 62047-3:2006 was approved by CENELEC as a European Standard without any modification.

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Annex ZA
(normative)

**Normative references to international publications
with their corresponding European publications**

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 62047-2	- ¹⁾	Semiconductor devices - Micro-electromechanical devices Part 2: Tensile testing method of thin film materials	EN 62047-2	2006 ²⁾
ISO 17561	- ¹⁾	Fine ceramics (advanced ceramics, advanced - technical ceramics) - Test method for elastic moduli of monolithic ceramics at room temperature by sonic resonance		-

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¹⁾ Undated reference.

²⁾ Valid edition at date of issue.

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62047-3

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**Dispositifs à semiconducteurs –
Dispositifs microélectromécaniques –**

**Partie 3:
Epreuve d'essai normalisée en
couche mince pour l'essai de traction**

(standards.iteh.ai)

**Semiconductor devices –
Micro-electromechanical devices –**

**Part 3:
Thin film standard test piece for tensile testing**

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International Electrotechnical Commission, 3, rue de Varembe, PO Box 131, CH-1211 Geneva 20, Switzerland
Telephone: +41 22 919 02 11 Telefax: +41 22 919 03 00 E-mail: inmail@iec.ch Web: www.iec.ch



Commission Electrotechnique Internationale
International Electrotechnical Commission
Международная Электротехническая Комиссия

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**SEMICONDUCTOR DEVICES –
MICRO-ELECTROMECHANICAL DEVICES –**

**Part 3: Thin film standard test piece
for tensile testing**

FOREWORD

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International Standard IEC 62047-3 has been prepared by IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

FDIS	Report on voting
47/1866/FDIS	47/1879/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.